



ISO/IEC JTC 1/SC 25/WG 3 N 643

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ISO/IEC JTC 1/SC 25/WG 3
Customer Premises Cabling
Secretariat: Germany (DIN)

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(Kyoto 81A)
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STATUS: This liaison report was approved by WG 3 at its meeting in Kyoto, Japan, 2002-02-25/-03-01.
ACTION ID: FYI
DUE DATE: n/a
REQUESTED: For information.
ACTION Mid-span power insertion will be on the agenda of the next meeting of SC 25/WG 3.

Due to the discussion in Kyoto it would be important for WG 3 to know whether mid-span power insertion will always use separate pairs, that is pairs which are not used for information transfer or whether there is also a need to provide this function for pairs used for information, e. g. when only two pairs are terminated at the TO. **The next meeting of WG 3 will take place near Washington, D.C., USA, 2002-09-23/26.**

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Liaison Report from ISO/IEC JTC 1/SC 25/WG 3 to IEEE 802.3 on mid-span power insertion

To: IEEE 802.3
From: ISO/IEC JTC 1/SC 25/WG 3
Subject: Mid-span power insertion
Date: March, 2002

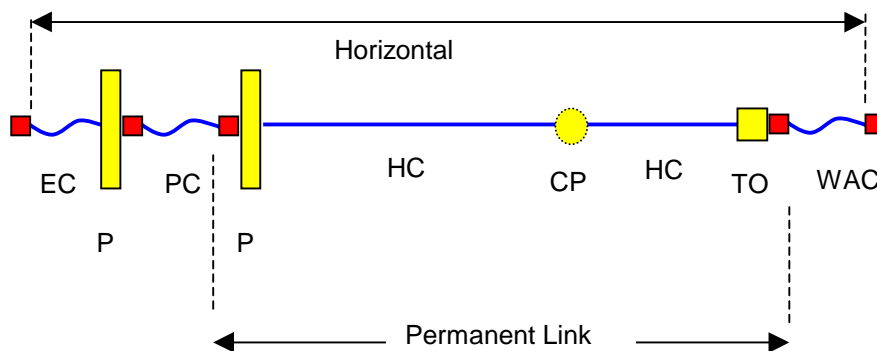
At their meeting in Kyoto (February 25 to March 1, 2002), ISO/IEC JTC1/SC 25/WG 3 considered the liaison report from IEEE on mid-span power insertion and approved the following answer.

SC25 WG3 would like to thank IEEE 802.3 for its liaison contribution (19 February 2002) concerning mid-span power insertion.

WG 3 concurs that mid-span power insertion equipment combines elements of generic cabling with an application-specific functionality. This equipment is "hybrid" by nature and should not be classified as LAN equipment.

WG 3 envisage many implementation concepts for mid-span power insertion equipment within generic cabling:

ISO/IEC 11801 Generic Cabling Model:



ISO/IEC 11801 2nd edition defines the channel characteristics for IEEE 802.3af remote powering and all supported classes of applications, including performance verification.

Generic cabling channel performance is assured for the above implementation concepts if the following requirements are met:

- When mid-span power insertion equipment replaces a generic cabling component or components, it shall meet the performance requirements of the component or components it replaces (e.g., patch cord, patch panel or combination thereof), regardless of the interfaces used for input and output connections.
- Placement of mid-span power insertion equipment shall be external to the permanent link.